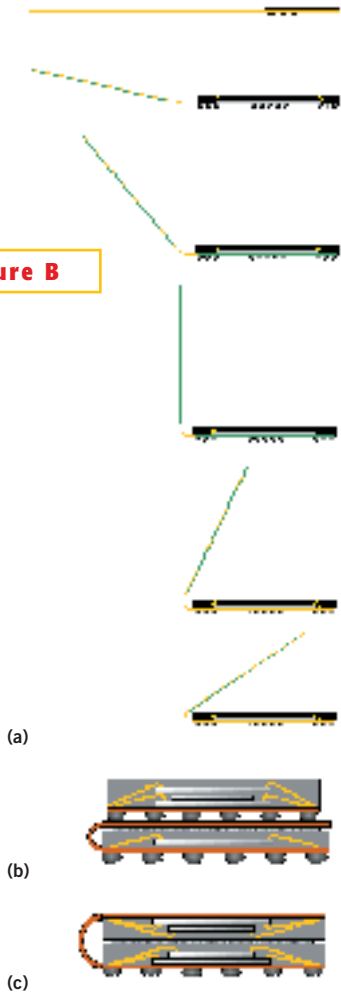


**Figure B**



Folded, stacked interconnect (a) creates quick time-to-market combinations of single-die and multichip packaged chips in logic-plus-memory (b) and memory-only (c) configurations (courtesy Intel).